



Date: September 6. 2016

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Rev: 1.0

Marking on device:

**VSXX05G**  
**PPPPPPPPPP**  
**YYWW**

where, VSXX05G = VS1205G, VS1005G or VS8005G

PPPPPPPPPP = Lot ID

YYWW = assembly Year and Week

**Order code:**

VS1205G-Q

VS1005G-Q

VS8005G-Q

**Product Name:**

VS1205G-Q

VS1005G-Q

VS8005G-Q

**Package:**

**88 LFGA (10x10x0.8) P0.40**

**REF:**

no	Part Name	Material Name	Component WT (mg)	Material Content (Element)	CAS#	Element Wt (%)	Element WT (mg)	WT% of total unit Wt	ppm
1	Die	Silicon Chip (204x205x7 mils)	11.446	Silicon	7440-21-3	100.00	11.446	4.080	40798.868
2	Substrate (Lead Frame)	HDL (10X10) LF ((A194FH))	117.588	Copper	7440-50-8	97.150	114.237	40.719	407192.884
				Fe	7439-89-6	2.500	2.940	1.048	10478.458
				P	7723-14-0	0.150	0.176	0.063	628.707
				Zn	7440-66-6	0.150	0.176	0.063	628.707
				Silver	7440-22-4	0.050	0.059	0.021	209.569
3	Mold Compound	EME G770HP	144.016	Silica(Amorphous) A	60676-86-0	75.5	108.732	38.757	387571.708
				Silica(Amorphous) B	7631-86-9	15	21.602	7.700	77001.002
				Epoxy Resin A	Trade Secret	3.0	4.320	1.540	15400.200
				Epoxy Resin B	Trade Secret	3.0	4.320	1.540	15400.200
				Phenol Resin	Trade Secret	3.0	4.320	1.540	15400.200
5	Bonding Wire	Copper wire (23 microns)	0.930	Copper	7440-50-8	97.100	0.903	0.322	3218.819
				Palladium	5/3/7440	2.900	0.027	0.010	96.134
6	Die Attach Material	CRM 1066C	2.314	Silver (Ag)	7440-22-4	72.000	1.666	0.594	5938.684
				Epoxy resin A	9003-36-5	15.000	0.347	0.124	1237.226
				Acid Anhydride A	19438-60-9	7.000	0.162	0.058	577.372
				Epoxy resin B	Trade Secret	3.000	0.069	0.025	247.445
				Acid Anhydride B	85-42-7	3.000	0.069	0.025	247.445
7	Plating (Solder)	Sn 100%	4.253	Tin (Sn)	7440-31-5	99.99	4.253	1.516	15158.154
				Other	Trade Secret	0.01	0.000425	0.000	1.516
Total Unit Weight =			280.547				280.547	100	100000